

Electronic components - Long-term storage of
electronic semiconductor devices - Part 7:
Micro-electromechanical devices

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

See Eesti standard EVS-EN IEC 62435-7:2021 sisaldab Euroopa standardi EN IEC 62435-7:2021 ingliskeelset teksti.	This Estonian standard EVS-EN IEC 62435-7:2021 consists of the English text of the European standard EN IEC 62435-7:2021.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation and Accreditation.
Euroopa standardimisorganisatsioonid on teinud Euroopa standardi rahvuslikele liikmetele kättesaadavaks 22.01.2021.	Date of Availability of the European standard is 22.01.2021.
Standard on kättesaadav Eesti Standardimis-ja Akrediteerimiskeskusest.	The standard is available from the Estonian Centre for Standardisation and Accreditation.

Tagasisidet standardi sisu kohta on võimalik edastada, kasutades EVS-i veebilehel asuvat tagasiside vormi või saates e-kirja meiliaadressile standardiosakond@evs.ee.

ICS 31.020

Standardite reprodutseerimise ja levitamise õigus kuulub Eesti Standardimis- ja Akrediteerimiskeskusele. Andmete paljundamine, taastekitamine, kopeerimine, salvestamine elektroonsesse süsteemi või edastamine ükskõik millises vormis või millisel teel ilma Eesti Standardimis-ja Akrediteerimiskeskuse kirjaliku loata on keelatud.

Kui Teil on küsimusi standardite autorikaitse kohta, võtke palun ühendust Eesti Standardimis-ja Akrediteerimiskeskusega: Koduleht www.evs.ee; telefon 605 5050; e-post info@evs.ee

The right to reproduce and distribute standards belongs to the Estonian Centre for Standardisation and Accreditation. No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying, without a written permission from the Estonian Centre for Standardisation and Accreditation.

If you have any questions about copyright, please contact Estonian Centre for Standardisation and Accreditation: Homepage www.evs.ee; phone +372 605 5050; e-mail info@evs.ee

ICS 31.020

English Version

**Electronic components - Long-term storage of electronic
semiconductor devices - Part 7: Micro-electromechanical
devices
(IEC 62435-7:2020)**

Composants électroniques - Stockage de longue durée des
dispositifs électroniques à semiconducteurs - Partie 7:
Dispositifs microélectromécaniques
(IEC 62435-7:2020)

Elektronische Bauteile - Langzeitlagerung elektronischer
Halbleiterbauelemente - Teil 7: Bauelemente der
Mikrosystemtechnik
(IEC 62435-7:2020)

This European Standard was approved by CENELEC on 2021-01-08. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Republic of North Macedonia, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 47/2664/FDIS, future edition 1 of IEC 62435-7, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62435-7:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-10-08
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-01-08

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 62435-7:2020 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC/TR 62258-3 NOTE Harmonized as CLC/TR 62258-3

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60721-3-1	-	Classification of environmental conditions - Part 3-1: Classification of groups of environmental parameters and their severities - Storage	EN IEC 60721-3-1	-
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN IEC 60749-20	-
IEC 60749-20-1	-	Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat	-	-
IEC 62435-2	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 2: Deterioration mechanisms	EN 62435-2	-
IEC 62435-3	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 3: Data	EN IEC 62435-3	-
IEC 62435-4	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 4: Storage	EN IEC 62435-4	-
IEC 62435-5	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 5: Die and wafer devices	EN 62435-5	-

INTERNATIONAL STANDARD

NORME INTERNATIONALE

Electronic components – Long-term storage of electronic semiconductor devices –

Part 7: Micro-electromechanical devices

Composants électroniques – Stockage de longue durée des dispositifs électroniques à semiconducteurs –

Partie 7: Dispositifs microélectromécaniques



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2020 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

IEC publications search - webstore.iec.ch/advsearchform

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: sales@iec.ch.

Electropedia - www.electropedia.org

The world's leading online dictionary on electrotechnology, containing more than 22 000 terminological entries in English and French, with equivalent terms in 16 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

IEC Glossary - std.iec.ch/glossary

67 000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Recherche de publications IEC -

webstore.iec.ch/advsearchform

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études,...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

IEC Just Published - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et une fois par mois par email.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: sales@iec.ch.

Electropedia - www.electropedia.org

Le premier dictionnaire d'électrotechnologie en ligne au monde, avec plus de 22 000 articles terminologiques en anglais et en français, ainsi que les termes équivalents dans 16 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

Glossaire IEC - std.iec.ch/glossary

67 000 entrées terminologiques électrotechniques, en anglais et en français, extraites des articles Termes et Définitions des publications IEC parues depuis 2002. Plus certaines entrées antérieures extraites des publications des CE 37, 77, 86 et CISPR de l'IEC.

INTERNATIONAL STANDARD

NORME INTERNATIONALE

Electronic components – Long-term storage of electronic semiconductor devices –

Part 7: Micro-electromechanical devices

Composants électroniques – Stockage de longue durée des dispositifs électroniques à semiconducteurs –

Partie 7: Dispositifs microélectromécaniques

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.020

ISBN 978-2-8322-9147-4

Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.

CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	7
4 Storage considerations	9
4.1 Overview of MEMS applications	9
4.2 Failure mechanisms	9
4.2.1 Occurrence of failure and driving force	9
4.2.2 Storage environment and mitigation for stimuli to prevent failure	12
4.3 Materials management.....	13
4.4 Storage media	13
4.5 Documentation/paper lot identifiers	14
4.6 Inventory check.....	14
4.7 Inventory dry packing refreshing	14
4.8 Inventory re-assessment.....	14
5 Baseline long-term storage requirements.....	14
5.1 General.....	14
5.2 Moisture sensitivity designation	15
5.3 Dry packing for storage	15
5.4 Non-moisture sensitive device storage	15
5.4.1 General	15
5.4.2 Storage media	15
5.4.3 Lot data and labelling	15
5.5 Storage of MEMS devices before assembly – Wafer level and die level storage	15
5.6 Storage of moisture sensitive finished devices	15
5.6.1 Moisture barrier bag	15
5.6.2 Dunnage.....	16
5.6.3 Humidity indicator card	16
5.6.4 Desiccant	16
5.6.5 Labelling.....	16
5.6.6 Lot data and labelling	16
5.6.7 Storage environment	17
5.6.8 Process (temperature) sensitivity designation	17
Annex A (informative) Packaged or finished device storage environment considerations	18
Bibliography.....	19
Table 1 – Failure mechanisms in storage and stimuli to mitigate during storage.....	10
Table 2 – Long-term environment – sustained condition requirements	13
Table 3 – Considerations for management, control and documentation during storage.....	13
Table A.1 – Long-term storage environment – sustained condition considerations	18

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRONIC COMPONENTS – LONG-TERM STORAGE
OF ELECTRONIC SEMICONDUCTOR DEVICES –****Part 7: Micro-electromechanical devices****FOREWORD**

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

IEC 62435-7 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2664/FDIS	47/2669/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62435 series, published under the general title *Electronic components – Long-term storage of electronic semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This document applies to the long-term storage of electronic components.

This is a standard for long-term storage (LTS) of electronic devices drawing on the best long-term storage practices currently known. For the purposes of this document, LTS is defined as any device storage whose duration may be more than 12 months for product scheduled for long duration storage. While intended to address the storage of unpackaged semiconductors and packaged electronic devices, nothing in this document precludes the storage of other items under the storage levels defined herein.

Although it has always existed to some extent, obsolescence of electronic components and particularly of integrated circuits, has become increasingly intense over the last few years.

Indeed, with the existing technological boom, the commercial life of a component has become very short compared with the life of industrial equipment such as that encountered in the aeronautical field, the railway industry or the energy sector.

The many solutions enabling obsolescence to be resolved are now identified. However, selecting one of these solutions should be preceded by a case-by-case technical and economic feasibility study, depending on whether storage is envisaged for field service or production, for example:

- remedial storage as soon as components are no longer marketed;
- preventive storage anticipating declaration of obsolescence.

Taking into account the expected life of some installations, sometimes covering several decades, the qualification times, and the unavailability costs, which can also be very high, the solution to be adopted to resolve obsolescence should often be rapidly implemented. This is why the solution retained in most cases consists in systematically storing components which are in the process of becoming obsolescent.

The technical risks of this solution are, a priori, fairly low. However, it requires perfect mastery of the implemented process and especially of the storage environment, although this mastery becomes critical when it comes to long-term storage.

All handling, protection, storage and test operations are recommended to be performed according to the state of the art.

The application of the approach proposed in this document in no way guarantees that the stored components are in perfect operating condition at the end of this storage. It only comprises a means of minimizing potential and probable degradation factors.

Some electronic device users have the need to store electronic devices for long periods of time. Lifetime buys are commonly made to support production runs of assemblies that well exceed the production timeframe of their individual parts. This puts the user in a situation requiring careful and adequate storage of such parts to maintain the as-received solderability and minimize any degradation effects to the part over time. Major degradation concerns are moisture, electrostatic fields, ultraviolet light, large variations in temperature, air-borne contaminants, and outgassing.

Warranties and sparing also present a challenge for the user or repair agency as some systems have been designated to be used for long periods of time, in some cases for up to 40 years or more. Some of the devices needed for repair of these systems will not be available from the original supplier for the lifetime of the system or the spare assembly may be built with the original production run but then require long-term storage. This document was developed to provide a standard for storing electronic devices for long periods of time. For storage of devices that are moisture sensitive but that do not need to be stored for long periods of time, refer to IEC TR 62258-3.

Long-term storage assumes that the device is going to be placed in uninterrupted storage for a number of years. It is essential that it is useable after storage. Particular attention should be paid to storage media surrounding the devices together with the local environment.

These guidelines do not imply any warranty of product or guarantee of operation beyond the storage time given by the manufacturer.

The IEC 62435 series is intended to ensure that adequate reliability is achieved for devices in user applications after long-term storage. Users are encouraged to request data from suppliers to applicable specifications to demonstrate a successful storage life as requested by the user. These standards are not intended to address built-in failure mechanisms that would take place regardless of storage conditions.

These standards are intended to give practical guide to methods of long-duration storage of electronic components where this is intentional or planned storage of product for a number of years. Storage regimes for work-in-progress production are managed according to company internal process requirements and are not detailed in this series of standards.

The overall standard series is split into a number of parts. Parts 1 to 4 apply to any long-term storage and contain general requirements and guidance, whereas Parts 5 to 9 are specific to the type of product being stored. It is intended that the product specific part should be read alongside the general requirements of Part 1 to 4.

Electronic components requiring different storage conditions are covered separately starting with Part 5.

The structure of the IEC 62435 series as currently conceived is as follows:

- Part 1 – General
- Part 2 – Deterioration mechanisms
- Part 3 – Data
- Part 4 – Storage
- Part 5 – Die and wafer devices
- Part 6 – Packaged or finished devices
- Part 7 – Micro-electromechanical devices – MEMS
- Part 8 – Passive electronic devices
- Part 9 – Special cases